Diamond Slurries

High performance slurries for scalable polishing of diamond substrates and films

Entegris is the market leader in diamond polishing slurries. They are designed to meet various specifications for polishing polycrystalline diamond, monocrystalline diamond, and diamond films in a wide range of applications. Our advanced formulations provide high polishing rates, up to 10 times faster than conventional processes, while maintaining uniformity, low sub-surface damage, and low defectivity/scratches. Our slurries are high-volume manufacturing (HVM) ready. Custom solutions are available upon request.

Our HDD nanodiamond slurry solutions comprise of 100 nm – 450 nm diamonds used in both finishing slurries and rough lapping processes. The formulations can be used in both fixed and floating abrasive lapping plates. The unique swarf disper-sion chemistry helps protect against abrasion during lapping. The formulation contains virtually no ionic material and is designed to afford corrosion protection for thin deposited metals. The organic molecules are carefully formulated to enhance removal rates and disperse swarf and diamonds.



APPLICATIONS

· Polishing substrates for optical applications

FEATURES & BENEFITS

Achieve high removal rates with no sub-surface damage and excellent stability and dispersion	
Enable high-volume manufacturing scale-up	
Low cost of ownership	
Provide localized quick-turn and customized solutions	
Slurry development begins with the customer's application requirements at the forefront	
Our applications engineers work with customers to ensure that chemistries are optimized for target parameters and process conditions	



SPECIFICATIONS

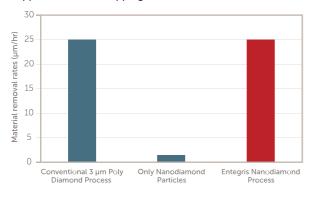
Product family	Process step	Polishing face best optimized for	Key features	Material removal rate (MRR)
DM-1000 series	Final finish, CMP	Polycrystalline diamond and diamond films	 Low surface roughness Ra <1 nm Diamond films Ra <0.2 nm 	N/A
DM-3000 series	Bulk polish	Monocrystalline and polycrystalline diamond	 High removal and low surface roughness Monocrystalline Ra <0.2 nm Polycrystalline Ra <3 nm 	0.2 - 1 µm/hr (depending on diamond type)

HDD Magnetic Head Polishing

Product family	Process step	Key features
Microlap 305E-170	Rough lap, intermediate polishing step	 High removal and low surface roughness High surface finish (<5 Å) Minimal embedding of diamond into substrate
Microlap 305E- 350, Microlap 305E-450	Bulk polishing of magnetic head	High stock removalMinimal embedding of diamond into substrate
Microlap 305E-100	Finishing polish	 Optimized removal rates with minimal dishing High surface finish (<2 Å) Minimal embedding of diamond into substrate Zero corrosion

PERFORMANCE DATA

Sapphire Diamond Lapping Removal Rates



FOR MORE INFORMATION

Please call your Regional Customer Service Center today to learn what Entegris can do for you. Visit entegris.com and select the Contact Us link to find the customer service center nearest you.

TERMS AND CONDITIONS OF SALE

All purchases are subject to Entegris' Terms and Conditions of Sale. To view and print this information, visit entegris.com and select the Terms & Conditions link in the footer.



Corporate Headquarters Customer Service 129 Concord Tel +1 952 556 4181 129 Concord 129 Concord Billerica, MA 01821

Fax +1 952 556 8022 Toll Free 800 394 4083

Entegris®, the Entegris Rings Design®, and other product names are trademarks of Entegris, Inc. as listed on entegris.com/trademarks. All third-party product names, logos, and company names are trademarks or registered trademarks of their respective owners. Use of them does not imply any affiliation, sponsorship, or endorsement by the trademark owner.

©2021-2022 Entegris, Inc. | All rights reserved. | Printed in the USA | 9000-11140ENT-0622